

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	4380	pair same (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane) same (first adj (surface link connect\$3 contact\$3)) same (second adj (surface link connect\$3 contact\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 09:27
L6	1	(pair near2 (short open load) near2 circuit) same (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane) same (first adj (surface link connect\$3 contact\$3)) same (second adj (surface link connect\$3 contact\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 09:29
L7	5	I5 and (pair near2 (short open load) near2 circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 09:29
L8	4	I7 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 11:39
L13	2	("5047752").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/16 11:44
S1	418	(324/601.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 08:16
S2	114	(324/600.ccls.) and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 10:53

S3	6	((("6348804") or ("5407752") or ("4858160"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 10:30
S4	2	("20040070405").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 10:30
S5	17	impedance adj standard adj substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 13:25
S6	14	S5 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 13:27
S7	2	("4,697,143").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 11:22
S8	3406	((impedance adj standard adj (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane)) ISS)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 13:34
S9	3237	S8 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 13:37

S10	13	S9 and (oscill\$7 VNA (vector adj network adj anal\$5)) near3 (\$2adjust\$ calibrat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:09
S11	18	impedance adj standard adj (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 09:23
S12	15	S11 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 13:46
S13	21871	(oscill\$7 VNA (vector adj network adj anal\$5)) near3 (\$2adjust\$ calibrat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 13:46
S14	20561	S13 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:04
S15	2	S14 and impedance adj standard adj (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane assembly unit system device apparatus machine mechanism section station means module set instrument tool circuit equipment)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 13:52
S16	586	S14 and impedance adj2 (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:33

S17	45	S1 and impedance adj2 (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:00
S18	20	S2 and impedance adj2 (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:03
S19	168	S16 and electrical\$3 near2 (connect\$3 contact\$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:35
S20	141	S19 and first same second	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 14:37
S21	6	S19 and (first adj (surface link connect\$3 contact\$3)) same (second adj (surface link connect\$3 contact\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:05
S22	17689	(surface link connect\$3 contact\$3) same impedance adj2 (substrate material \$5film coat\$3 layer sheet pad wafer film lamina level plane circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:03
S23	16924	S22 and @ad<"20030923"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/02/16 09:29

S24	668	S23 and (first adj (surface link connect\$3 contact\$3)) same (second adj (surface link connect\$3 contact\$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:05
S25	10	S24 and (oscill\$7 VNA (vector adj network adj anal\$5)) near3 (\$2adjust\$ calibrat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:37
S26	2	S2 and (oscill\$7 VNA (vector adj network adj anal\$5)) near3 (\$2adjust\$ calibrat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:37
S27	80	S1 and (oscill\$7 VNA (vector adj network adj anal\$5)) near3 (\$2adjust\$ calibrat\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:38
S28	1	S26 and (surface link connect\$3 contact\$3) same via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:44
S29	33	S27 and (surface link connect\$3 contact\$3) same via	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:39
S30	70699	via and calibration	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:45

S31	386	vna		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:45
S32	57	S30 and S31		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:45
S33	52	S32 and @ad<"20030923"		US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/22 15:45